IPC ASSOCIATION CONNECTED ELECTRONICS INDUST	© Copyright 2005. IF	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.				This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lowel level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.									
752-21.1		IPC Web Site for Information on IPC-1752 Standard Form Typ http://www.ipc.org/IPC-175x Distribute				e * Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Mater						s and Mfg I	nformatio	on	
Supplier Info	rmation														
Company name*			Company unique ID			Ţ	Unique ID Authority					Response Date*			
nsemi												2023-06-08			
Contact Name		Title - Contact			I	Phone - Contact*				I	Email - Contact*				
Product-Env-Ste	wards	Product Enviro Compliance				NA					Product-Env-Stewards@onsemi.com				
uthorized Repr	esentative*	Title - Representative			I	Phone - Representative*				I	Email - Representative*				
Product-Env-Stewards			Product Enviro Compliance				NA					Product-Env-Stewards@onsemi.com			
Reque	ester Item Number	er Item Number Mfr Item Number Mfr Item Name FAN7383MX Half bridge gate		m Number Mfr Item Name			Effective Date	e Version	n N	Manufacturing Site		Wei	ight*	UOM	Unit Type
				driver	iver 202			7	TH2		137	.765	mg	Each	
Ianufacturin	g Proccess Informat	ion						•							
Termin	al Plating / Grid Array Material		Terminal Base Alloy		-STD-020 MSL Rating		Peak Process Body Tempera		Temperatui	ure Max Time at Peak Ten		emperature	ure Number of Reflow Cycles		
Precious metal (e.g. Ag,Au, NiPdAu) (no Sn)		dAu) (no	CU Alloy		1		260		С	30	seco		3		
Comments															
vel 1 - maximun	n time at peak temperatu	re during so	ldering is 10-3	30 seconds											
or more informa	ation regarding material o	composition	please refer to	page 3											

RoHS Material Composition Declaration			Declaration Type *	Detail	ed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU  RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).											
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on informationprovided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies of Supplier's Standard Terms and Conditions of Sale applicable to such part shall apply.											
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted						
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the						

## **Homogeneous Material Composition Declaration for Electronic Products**

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	0.28	mg	Supplier	Silicon (Si)	7440-21-3		0.28	mg
Die Attach	0.13	mg	Supplier	Ethylene glycol dicyclopentenyl ether methacrylate	68586-19-6		0.0045	mg
			Supplier	Bis(a,a-dimethylbenzyl) Peroxide	80-43-3		0.0008	mg
			Supplier	Silver (Ag)	7440-22-4		0.1246	mg
Lead Frame	68.695	mg	Supplier	Zinc (Zn)	7440-66-6		0.0893	mg
			Supplier	Iron (Fe)	7439-89-6		1.6143	mg
			Supplier	Copper (Cu)	7440-50-8		66.9364	mg
			Supplier	Phosphorus (P)	7723-14-0		0.055	mg
Mold Compound-Black	67.22	mg		Epoxy resin	proprietary data		4.0332	mg
			Supplier	Phenolic Resin	Proprietary Data		4.0332	mg
			Supplier	Carbon Black (C)	1333-86-4		0.3361	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		57.137	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		1.6805	mg
Plating	1.21	mg	Supplier	Silver (Ag)	7440-22-4		0.015	mg
			Supplier	Palladium (Pd)	7440-05-3		0.034	mg
			В	Nickel (Ni)	7440-02-0		0.891	mg
			Supplier	Gold (Au)	7440-57-5		0.27	mg
Wire Bond - Au	0.23	mg	Supplier	Gold (Au)	7440-57-5		0.23	mg